7/20/2007

RELIABILITY MONITOR REPORT
FOR

SVL S4.5 Process

Dallas Semiconductor

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Dallas, TX 75244-3292

This Report was prepared by
Dallas Semiconductor Reliability Engineering

Summary:

The data in the tables that follow was generated as the result of an on-going Process Reliability Monitor. The products covered by this process monitor are:

MAX6618	MAX6621

The calculated failure rate for devices using this process is:

FAILURE RATE: **MTTF (YRS): 5288** **FITS: 21.6**

The parameters used to calculate this failure rate are as follows:

Cf: 60% **Ea: 0.7** **Tu: 25 °C**

The reliability data follows. A the start of this data is the process information. The next section is the detailed reliability data for each stress. The reliability data section includes the latest data available. This report covers data between 7/1/2006 and 6/30/2007 .

Device Information:

Process: SVL S4.5 Process
Interconnect: Aluminum / 1% Silicon / 0.5% Copper
Gate Oxide Thickness:

OPERATING LIFE

DESCRIPTION	DATE CODE	TEST VEHICLE	CONDITION	READPOINT	QUANTITY	FAILS	FA NO
HIGH TEMP OP LIFE	0702	MAX6618	125C, 3.6V (PSA) & 1.1V (PSB)	1000 HRS	45	0	
					Total:	**0**	

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